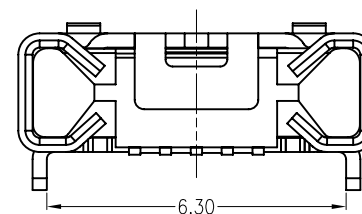
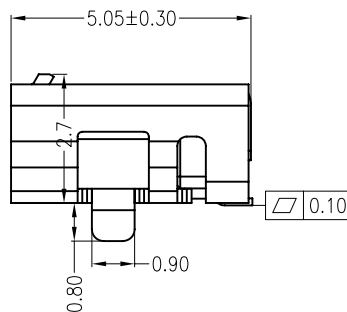
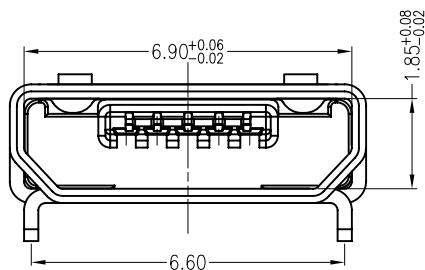
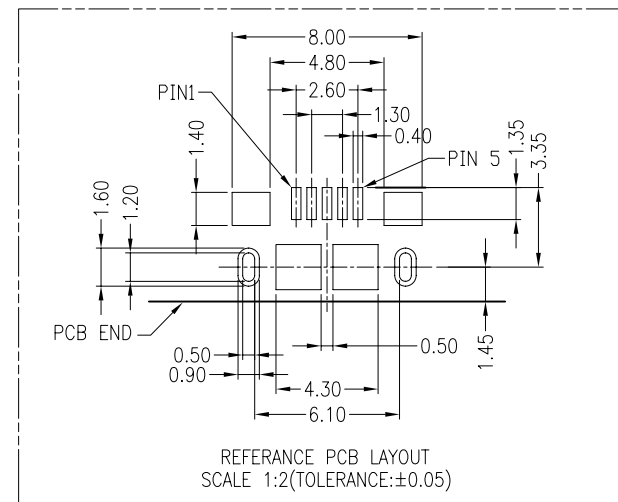
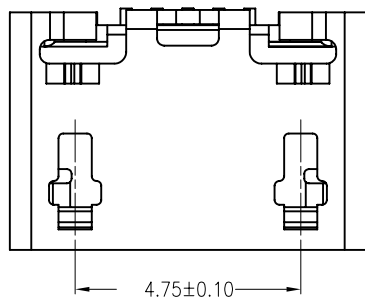


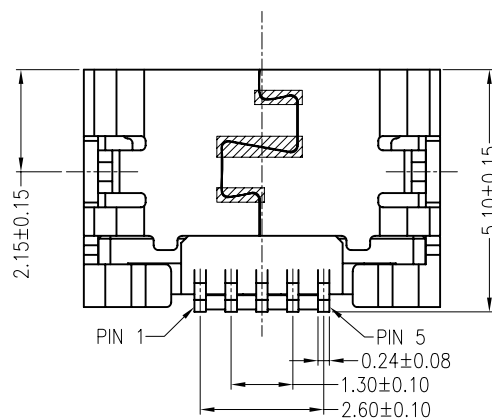
THE PART MEETS TECONN "GP001" COMPLIANCE



A4A0504-D-XX-R


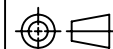
Mating Area plating

- 01: Au 1u"Min.
- 03: Au 3u"Min.
- 05: Au 5u"Min.
- 10: Au 10u"Min.
- 15: Au 15u"Min.
- 30: Au 30u"Min.



- 1.Contact Resistance:30mOHM Max.;
- 2.Dielectric Withstanding Voltage:100V AC For 1 Minute;
- 3.Insulation Resistance:1000M OHM Min.;
- 4.Mating And Unmating Force:
Mating Force:35N Max/Unmating Force:8N Min;
- 5.Durability:10000 Cycles;

Item	Title	Material	Dispose
1	Shell	Stainless Steel	Matte Tin 80u"min.
2	Terminal	Copper Alloy	Mating Area:See P/N Solder Tails:Gold 2u"Min. Under: Nickel 50~100u"Min.
3	InsertMolding	LCP	UL94V-0

X. ± 0.35	APPD:	TITLE:	 泰康电子 TECONN
.X ± 0.25	Henry Sun	MICRO USB B/F 5PIN SMT	
.XX ± 0.15	CHKD:	PART NO:	
.XXX±	DR:	A4A0504-D-XX-R	
X' ± 2'	Kevin Han	DWG NO:	
.X' ± 1.5'		C-44A0504-D-XX-R	CUSTOMER DRAWING
 UNITS: mm		SCALE: 1:1	SHEET:1OF1
			REV: A

A	TE2011-0016	New Drawing	2011/01/11
REV	ECN NO	DESCRIPTION	DATE